

GNSS Front-End Module

■ FEATURES

- AEC-Q100 grade 2 qualified
- Low supply voltage 2.8V typ.
- Low current consumption 3.7mA typ.
- High gain 16.0dB typ.
- Low noise figure
 - 1.50dB typ. @f=1575MHz
 - 1.65dB typ. @f=1597 to 1606MHz
 - 1.70dB typ. @f=1559 to 1591MHz
- High out band rejection
 - 55dBc typ. @f=704 to 915MHz, relative to 1575MHz 43dBc typ. @f=1710 to 1980MHz, relative to 1575MHz 51dBc typ. @f=2400 to 2500MHz, relative to 1575MHz
- Integrated pre-SAW filter and LNA
- Small package size
 - HFFP10-HH 1.5mmx1.1mm (typ.), t=0.5mm (max.)
- RoHS compliant and Halogen Free, MSL1

APPLICATION

- •GNSS application for automotive
- •GNSS active antenna

■ BLOCK DIAGRAM (HFFP10-HH)





(Top view)

■ GENERAL DESCRIPTION

The NJG1159PHH-A is a front-end module (FEM) designed for GNSS including GPS, GLONASS, BeiDou, and Galileo applications. This FEM offers low noise figure, high linearity, and high out-band rejection characteristics brought by included high performance pre-SAW filter and low noise amplifier (LNA). The stand-by mode contributes to reduce current consumption.

Its wide operating temperature range from -40 to +105°C is suitable for automotive application.

This FEM is suitable for small size application by included one SAW filter, only two external components, and very small package HFFP10-HH that is 1.5x1.1mm.

TRUTH TABLE

"H"=V_{CTL(H)}, "L"=V_{CTL(L)}

VCTL	Mode			
Н	Active mode			
L	Stand-by mode			

PIN CONFIGURATION

PIN NO.	SYMBOL	DESCRIPTION
1	VDD	Supply voltage terminal
2	VCTL	Control voltage terminal
3	GND	Ground terminal
4	PrelN	RF input terminal to
4	FIGIN	Pre-SAW filter
5	GND	Ground terminal
6	PreOUT	RF output terminal from
0	FIEOUI	Pre-SAW filter
7	LNAIN	RF input terminal to LNA
8	LNAOUT	RF output terminal from LNA
9	GND	Ground terminal
10	GND	Ground terminal

PRODUCT NAME INFORMATION

<u>NJG1159</u>	<u>PHH</u>	<u>-A</u>	<u>(TE1)</u>	
	I	L	۱ L	
Part number	Package	Auto	motive	Taping form

ORDERING INFORMATION

PART NUMBER	PACKAGE OUTLINE	RoHS	HALOGEN- FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ (pcs.)
NJG1159PHH-A	HFFP10-HH	Yes	Yes	Au	59A	4.6	3,000

■ ABSOLUTE MAXIMUM RATINGS

		l _a =+25°0	$S, Z_s = Z_i = 50\Omega$
PARAMETER	SYMBOL	RATINGS	UNIT
Supply voltage	Vdd	5.0	V
Control voltage	VCTL	5.0	V
Input power	P _{IN} (inband) ⁽¹⁾	+10	dBm
	P _{IN} (outband) ⁽²⁾	+25	dBm
Power dissipation	P _D ⁽³⁾	560	mW
Operating temperature	T _{opr}	-40 to +105	°C
Storage temperature	T _{stg}	-40 to +110	°C

(1): V_{DD}=2.8V, f=1575, 1597 to 1606, 1559 to 1591MHz

(2): V_{DD}=2.8V, f=50 to 1460, 1710 to 4000MHz

(3): 4-layer FR4 PCB without through-hole (101.5x114.5mm), Tj=110°C

■ POWER DISSIPATION VS.AMBIENT TEMPERATURE

Please note small non-lead package generally has low thermal dissipation characteristic, attention is recommended in designing of thermal radiation.



Power Dissipation-Ambient Temperature

■ ELECTRICAL CHARACTERISTICS 1 (DC)

PARAMETER	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V _{DD}		1.5	2.8	3.3	V
Control Voltage (High)	V _{CTL(H)}		1.5	1.8	3.3	V
Control Voltage (Low)	Vctl(L)		0	0	0.3	V
Supply Current 1	IDD1	RF OFF, V _{DD} =2.8V, V _{CTL} =1.8V	-	3.7	6.5	mA
Supply Current 2	IDD2	RF OFF, Vdd=2.8V, Vctl=0V	-	0.1	5.0	μA
Control Current	Іст∟	Vcn=1.8V	-	5.0	15.0	μA

(General conditions: $T_a = 25^{\circ}C$, with application circuit)

■ ELECTRICAL CHARACTERISTICS 2 (RF)

General conditions: V_{DD}=2.8V, V_{CTL}=1.8V, f_{RF}=1575MHz, 1597 to 1606MHz, 1559 to 1591MHz,

$T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit						circuit
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Small Signal Gain (GPS)	GainGPS	f=1575MHz (GPS) Exclude PCB, Connector Losses (0.17dB)	13.5	16.0	-	dB
Small Signal Gain (GLONASS)	GainGLN	f=1597 to 1606MHz (GLONASS) Exclude PCB, Connector Losses (0.17dB)	13.0	16.5	-	dB
Small Signal Gain (BeiDou, Galileo)	GainBG	f=1559 to 1591MHz (BeiDou, Galileo) Exclude PCB, Connector Losses (0.17dB)	13.0	16.0	-	dB
Noise Figure (GPS)	NFGPS	f=1575MHz (GPS)Exclude PCB, Connector Losses (0.09dB)	-	1.50	2.35	dB
Noise Figure (GLONASS)	NFGLN	f=1597 to 1606MHz (GLONASS) Exclude PCB, Connector Losses (0.09dB)	-	1.65	2.70	dB
Noise Figure (BeiDou, Galileo)	NFBG	f=1559 to 1591MHz (BeiDou, Galileo) Exclude PCB, Connector Losses (0.09dB)	-	1.70	2.80	dB
Input Power at 1dB Gain Compression Point	P-1dB(IN)	f=1575, 1597 to 1606, 1559 to 1591MHz	-15.0	-10.0	-	dBm
Low Band Rejection	BR_L	f=704 to 915MHz, relative to 1575MHz	41	55	-	dBc
High Band Rejection	BR_H	f=1710 to 1980MHz, relative to 1575MHz	23	43	-	dBc
WLAN Band Rejection	BR_W	f=2400 to 2500MHz, relative to 1575MHz	38	51	-	dBc

ELECTRICAL CHARACTERISTICS

Conditions: V_{DD} =2.8V, V_{CTL} =1.8V, Ta=25°C, Z_s = Z_i =50 Ω , with application circuit



■ ELECTRICAL CHARACTERISTICS

Conditions: $V_{DD}=2.8V$, $V_{CTL}=1.8V$, $Z_s=Z_l=50\Omega$, with application circuit



1.2

1.0

0.8

0.6

0.4

0.2

0.0

(μA) @Standby Mode

8

■ ELECTRICAL CHARACTERISTICS

Conditions: V_{CTL}=1.8V, Ta=25°C, Z_s=Z_i=50 Ω , with application circuit



■ APPLICATION CIRCUIT



<PARTS LIST>

Part ID	Note		
11	LQW15AN_00 Series		
LI	(MURATA)		
C1	GRM03 Series		
	(MURATA)		

Automotive NJG1159PHH-A

■ EVALUATION BOARD



PCB Substrate: FR-4 Thickness: 0.2mm Microstrip line width: 0.4mm (Z_0 =50 Ω) Size: 14.0mm x 14.0mm

<PCB LAYOUT GUIDELINE>



PRECAUTIONS

• Please layout ground pattern under this FEM in order not to couple with RFIN and RFOUT terminal.

• All external parts should be placed as close as possible to the FEM.

• For good RF performance, all GND terminals must be connected to PCB ground plane of substrate, and via-holes for GND should be placed near the FEM.

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■ RECOMMENDED FOOTPRINT PATTERN (HFFP10-HH Package) <Reference>



■ NOISE FIGURE MEASUREMENT BLOCK DIAGRAM

Measuring instruments		
NF Analyzer	: Keysight N8973A	
•		
Noise Source	: Keysight 346A	
Setting the NF analyzer		
Measurement mode for	1	
Device under test	: Amplifier	
System downconve	ter : off	
Mode setup form		
Sideband	: LSB	
Averages	: 16	
Average mode	: Point	
Bandwidth	: 4MHz	
Loss comp	: off	
Tcold	: setting the temperature of noise source (303.15K)	



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■ PACKAGE OUTLINE (HFFP10-HH)



■ PACKING SPECIFICATION (HFFP10-HH)

TAPING DIMENSIONS



REEL DIMENSIONS



SYMBOL	DIMENSION	REMARKS
Α	1.4±0.1	BOTTOM DIMENSION
В	1.8±0.1	BOTTOM DIMENSION
DO	1.5 ^{+0.1}	
D1	0.5±0.05	
E	1.75±0.1	
F	3.5±0.05	
P0	4.0±0.1	
P1	4.0±0.1	
P2	2.0±0.05	
Т	0.25±0.05	
T2	0.7±0.1	
W	8.0±0.2	
W1	5.3±0.2	THICKNESS100 μ m max

Unit: mm

SYMBOL	DIMENSION
Α	ϕ 180 $_{-1.5}^{0}$
В	$\phi 66 \pm 0.5$
С	φ 13±0.2
D	φ 21±0.8
E	2±0.5
W	9 ^{+1.0}
W1	1. 2

TAPING STATE



< Se	Sealing with covering tape >				
Empty tape	Devices	Empty tape			
more than 240mm	3000pcs/reel	more than 400mm			

PACKING STATE



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REVISION HISTORY

Date	Revision	Changes
15.Nov.2016	Ver.1.0	New Release Automotive spec
19.Jul.2017	Ver.1.1	Changed package suffix from H to A Updated ELECTRICAL CHARACTERISTICS 1 (DC) Updated ELECTRICAL CHARACTERISTICS 2 (RF) Added packing specification
19.Oct.2018	Ver.1.2	Revised features Revised caution
08.Nov.2018	Ver.1.3	Revised MARK INFORMATION Revised ORDERING INFORMATION Revised weight
08.Jan.2019	Ver.1.4	Revised features Added APPLICATION Revised PRODUCT NAME INFORMATION Revised ORDERING INFORMATION Revised ELECTRICAL CHARACTERISTICS 2 (RF) Added POWER DISSIPATION VS.AMBIENT TEMPERATURE Revised caution

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 - 8-1. Quality Warranty Period

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8-2. Quality Warranty Remedies

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- 8-3. Remedies after Quality Warranty Period

With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.

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- 11. Warning for handling Gallium and Arsenic (GaAs) products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
- 12. Front end module product is hollow seal package type, and it is with the structure susceptible to stress from the outside. Therefore, note the following in relation to the contents, after conducting an evaluation. please use.
 - 12-1. After mounting this product, to implement the potting and transfer molding, please the confirmation of resistance to temperature changes and shrinkage stress involved in the molding.
 - 12-2. When mounted on the product, collet diameter please use more than 1mmφ. In addition, the value of static load is recommended mounting less than 5N.
 - 12-3. For dynamic load at the time of mounting. please use it after confirming in consideration of the contact area /speed /load.
- 13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



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